

Flip Chip Market by Packaging Technology (3D IC, 2.5D IC, and 2D IC), Bumping Technology (Solder Bumping, Gold Bumping, and Others), and Industry (Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace & Defense, and Others): Global Opportunity Analysis and Industry Forecast, 2020–2027

<https://marketpublishers.com/r/FC852983D2BEN.html>

Date: June 2020

Pages: 279

Price: US\$ 5,769.00 (Single User License)

ID: FC852983D2BEN

Abstracts

Flip chip, also known as controlled collapse chip connection (C4), is used for interconnecting semiconductor devices, such as IC chips, microscopic devices, micro sensors, and microprocessor to external circuitry while utilizing deposited solder bumps onto the chip pads. Use of flip chip interconnections offers numerous advantages over conventional wire bond, which includes superior thermal & electrical performance, reduced form factors, well-defined construction, substrate flexibility for varying performance requirements, and the highest I/O capability.

The growth of the global flip chip market is majorly driven by rise in need for circuit miniaturization, rise in trend in Internet of Things (IoT), and technological superiority over wire bonding. However, huge initial investment required for setting up new manufacturing facility and less options for customization are the restraints associated with flip chip, which hamper the market growth. Moreover, surge in demand for sensors in smartphone industry and increase in integration of flip chip in personal electronic devices such as PCs and mobiles are expected to offer lucrative opportunities for the market.

The global flip chip market is segmented on the basis of flip chip packaging technology, bumping technology, industry, and region. On the basis of bumping technology, the

market is divided into copper pillar, solder bumping, gold bumping, and others, including aluminum & conductive polymer bumping. The copper pillar segment dominates the market, as it is a next-generation flip chip interconnect, which meet current and future electronic device requirements. It serves as an ideal interconnect option for applications such as transceivers, embedded processors, and electrical processors.

On the basis of packaging technology, the market is categorized into 3D IC, 2.5D IC, and 2D IC. Among these, the 2.5D IC packaging segment dominated the market in 2019 owing to its several advantages such as superior capacity, improved performance, and minimal system space requirements, and low power consumption. Depending on industry, the market is fragmented into electronics, industrial, automotive & transport, healthcare, IT & telecommunication, aerospace & defense, and others. Region wise, it is analyzed across North America, Europe, Asia-Pacific, and LAMEA.

The market players operating in the flip chip market include IBM Corporation, Intel Corporation, Fujitsu Ltd., 3M, Samsung electronics Co., Ltd, Amkor Packaging Technology, Inc., TSMC, Ltd, Apple, Inc., Texas Instruments, Inc., and AMD, Inc. These major players have adopted various key development strategies such as business expansion, and new product launch, which help them to strengthen their foothold in the market.

KEY BENEFITS FOR STAKEHOLDERS

The study provides an in-depth analysis of the current & future trends of the market to elucidate the imminent investment pockets.

Information about key drivers, restraints, and opportunities and their impact analysis on the global flip chip market share is provided.

Porter's five forces analysis illustrates the potency of the buyers and suppliers operating in the global flip chip industry.

The quantitative analysis of the market from 2019 to 2027 is provided to determine the global flip chip market potential.

KEY MARKET SEGMENTS

By Packaging Technology

3D IC

2.5D IC

2D IC

By Bumping Technology

Copper Pillar

Solder Bumping

Gold Bumping

Others (Aluminum & Conductive Polymer)

By Industry

Electronics

Industrial

Automotive & Transport

Healthcare

IT & Telecommunication

Aerospace & Defense

Others

By Region

North America

U.S.

Canada

Europe

Germany

France

UK

Rest of Europe

Asia-Pacific

Japan

China

India

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

KEY MARKET PLAYERS

3M

Advanced Micro Devices, Inc.

Amkor Technology

Apple Inc.

Fujitsu Limited

Intel Corporation

International Business Machines Corporation

Samsung Electronics Co., Ltd.

Taiwan Semiconductor Manufacturing Company Limited

Texas Instruments Incorporated

Contents

CHAPTER 1: INTRODUCTION

- 1.1.REPORT DESCRIPTION
- 1.2.KEY BENEFITS FOR STAKEHOLDERS
- 1.3.KEY MARKET SEGMENTS
- 1.4.KEY MARKET PLAYERS
- 1.5.RESEARCH METHODOLOGY
 - 1.5.1.Secondary research
 - 1.5.2.Primary research
 - 1.5.3.Analyst tools & models

CHAPTER 2: EXECUTIVE SUMMARY

- 2.1.KEY FINDINGS
 - 2.1.1.Top impacting factors
 - 2.1.2.Top investment pockets
- 2.2.CXO PERSPECTIVE

CHAPTER 3: MARKET OVERVIEW

- 3.1.MARKET DEFINITION AND SCOPE
- 3.2.KEY FORCES SHAPING THE GLOBAL FLIP CHIP MARKET
- 3.3.VALUE CHAIN ANALYSIS
- 3.4.MARKET DYNAMICS
 - 3.4.1.Drivers
 - 3.4.1.1.Thriving portable electronic market and increasing popularity of internet of things (IoT)
 - 3.4.1.2.Usage in graphic cards and processors used in real world Solder Bumping
 - 3.4.1.3.Technological superiority over wire bonding
 - 3.4.2.Restrictant
 - 3.4.2.1.Higher cost and less customization options available in comparison to wire bonding
 - 3.4.3.Opportunity
 - 3.4.3.1.Impending need of high frequency in electronic gadget
- 3.5. COVID-19 IMPACT ANALYSIS ON CLOUD MIGRATION SERVICES MARKET
 - 3.5.1. Impact on market size
 - 3.5.2. Consumer trends, preferences, and budget impact

- 3.5.3. Regulatory framework
- 3.5.4. Economic impact
- 3.5.5. Key player strategies to tackle negative impact
- 3.5.6. Opportunity window

CHAPTER 4: GLOBAL FLIP CHIP MARKET, BY PACKAGING TECHNOLOGY

4.1.OVERVIEW

4.2.3D IC

- 4.2.1.Key market trends, growth factors, and opportunities
- 4.2.2.Market size and forecast, by region
- 4.2.3.Market analysis, by country

4.3.2.5D IC

- 4.3.1.Key market trends, growth factors, and opportunities
- 4.3.2.Market size and forecast, by region
- 4.3.3.Market analysis, by country

4.4.2D IC

- 4.4.1.Key market trends, growth factors, and opportunities
- 4.4.2.Market size and forecast, by region
- 4.4.3.Market analysis, by country

CHAPTER 5: GLOBAL FLIP CHIP MARKET, BY BUMPING TECHNOLOGY

5.1.OVERVIEW

5.2.COPPER PILLAR

- 5.2.1.Key market trends, growth factors, and opportunities
- 5.2.2.Market size and forecast, by region
- 5.2.3.Market analysis, by country

5.3.SOLDER BUMPING

- 5.3.1.Key market trends, growth factors, and opportunities
- 5.3.2.Market size and forecast, by region
- 5.3.3.Market analysis, by country

5.4.GOLD BUMPING

- 5.4.1.Key market trends, growth factors, and opportunities
- 5.4.2.Market size and forecast, by region
- 5.4.3.Market analysis, by country

5.5.OTHERS

- 5.5.1.Key market trends, growth factors, and opportunities
- 5.5.2.Market size and forecast, by region

5.5.3. Market analysis, by country

CHAPTER 6: GLOBAL FLIP CHIP MARKET, BY INDUSTRY VERTICAL

6.1. OVERVIEW

6.2. ELECTRONICS

6.2.1. Key market trends, growth factors, and opportunities

6.2.2. Market size and forecast, by region

6.2.3. Market analysis, by country

6.3. INDUSTRIAL

6.3.1. Key market trends, growth factors, and opportunities

6.3.2. Market size and forecast, by region

6.3.3. Market analysis, by country

6.4. HEALTHCARE

6.4.1. Key market trends, growth factors, and opportunities

6.4.2. Market size and forecast, by region

6.4.3. Market analysis, by country

6.5. AUTOMOTIVE & TRANSPORT

6.5.1. Key market trends, growth factors, and opportunities

6.5.2. Market size and forecast, by region

6.5.3. Market analysis, by country

6.6. IT & TELECOMMUNICATION

6.6.1. Key market trends, growth factors, and opportunities

6.6.2. Market size and forecast, by region

6.6.3. Market analysis, by country

6.7. AEROSPACE & DEFENSE

6.7.1. Key market trends, growth factors, and opportunities

6.7.2. Market size and forecast, by region

6.7.3. Market analysis, by country

6.8. OTHERS

6.8.1. Key market trends, growth factors, and opportunities

6.8.2. Market size and forecast, by region

6.8.3. Market analysis, by country

CHAPTER 7: GLOBAL FLIP CHIP MARKET, BY REGION

7.1. OVERVIEW

7.1.1. Market size and forecast, by region

7.2. NORTH AMERICA

7.2.1.Key market trends, growth factors, and opportunities

7.2.2.Market size and forecast, by packaging technology

7.2.3.Market size and forecast, by bumping technology

7.2.4.Market size and forecast, by industry vertical

7.2.5.Market analysis, by country

7.2.5.1.U.S.

7.2.5.1.1.Market size and forecast, by packaging technology

7.2.5.1.2.Market size and forecast, by bumping technology

7.2.5.1.3.Market size and forecast, by industry vertical

7.2.5.2.CANADA

7.2.5.2.1.Market size and forecast, by packaging technology

7.2.5.2.2.Market size and forecast, by bumping technology

7.2.5.2.3.Market size and forecast, by industry vertical

7.3.EUROPE

7.3.1.Key market trends, growth factors, and opportunities

7.3.2.Market size and forecast, by packaging technology

7.3.3.Market size and forecast, by bumping technology

7.3.4.Market size and forecast, by industry vertical

7.3.5.Market analysis, by country

7.3.5.1.GERMANY

7.3.5.1.1.Market size and forecast, by packaging technology

7.3.5.1.2.Market size and forecast, by bumping technology

7.3.5.1.3.Market size and forecast, by industry vertical

7.3.5.2.FRANCE

7.3.5.2.1.Market size and forecast, by packaging technology

7.3.5.2.2.Market size and forecast, by bumping technology

7.3.5.2.3.Market size and forecast, by industry vertical

7.3.5.3.UK

7.3.5.3.1.Market size and forecast, by packaging technology

7.3.5.3.2.Market size and forecast, by bumping technology

7.3.5.3.3.Market size and forecast, by industry vertical

7.3.5.4.SPAIN

7.3.5.4.1.Market size and forecast, by packaging technology

7.3.5.4.2.Market size and forecast, by bumping technology

7.3.5.4.3.Market size and forecast, by industry vertical

7.3.5.5.REST OF EUROPE

7.3.5.5.1.Market size and forecast, by packaging technology

7.3.5.5.2.Market size and forecast, by bumping technology

7.3.5.5.3.Market size and forecast, by industry vertical

7.4.ASIA-PACIFIC

7.4.1.Key market trends, growth factors, and opportunities

7.4.2.Market size and forecast, by packaging technology

7.4.3.Market size and forecast, by bumping technology

7.4.4.Market size and forecast, by industry vertical

7.4.5.Market analysis, by country

7.4.5.1.JAPAN

7.4.5.1.1.Market size and forecast, by packaging technology

7.4.5.1.2.Market size and forecast, by bumping technology

7.4.5.1.3.Market size and forecast, by industry vertical

7.4.5.2.CHINA

7.4.5.2.1.Market size and forecast, by packaging technology

7.4.5.2.2.Market size and forecast, by bumping technology

7.4.5.2.3.Market size and forecast, by industry vertical

7.4.5.3.INDIA

7.4.5.3.1.Market size and forecast, by packaging technology

7.4.5.3.2.Market size and forecast, by bumping technology

7.4.5.3.3.Market size and forecast, by industry vertical

7.4.5.4.AUSTRALIA

7.4.5.4.1.Market size and forecast, by packaging technology

7.4.5.4.2.Market size and forecast, by bumping technology

7.4.5.4.3.Market size and forecast, by industry vertical

7.4.5.5.REST OF ASIA-PACIFIC

7.4.5.5.1.Market size and forecast, by packaging technology

7.4.5.5.2.Market size and forecast, by bumping technology

7.4.5.5.3.Market size and forecast, by industry vertical

7.5.LAMEA

7.5.1.Key market trends, growth factors, and opportunities

7.5.2.Market size and forecast, by packaging technology

7.5.3.Market size and forecast, by bumping technology

7.5.4.Market size and forecast, by industry vertical

7.5.5.Market analysis, by country

7.5.5.1.LATIN AMERICA

7.5.5.1.1.Market size and forecast, by packaging technology

7.5.5.1.2.Market size and forecast, by bumping technology

7.5.5.1.3.Market size and forecast, by industry vertical

7.5.5.2.MIDDLE EAST

7.5.5.2.1.Market size and forecast, by packaging technology

7.5.5.2.2.Market size and forecast, by bumping technology

7.5.5.2.3. Market size and forecast, by industry vertical
7.5.5.3. AFRICA

7.5.5.3.1. Market size and forecast, by packaging technology

7.5.5.3.2. Market size and forecast, by bumping technology

7.5.5.3.3. Market size and forecast, by industry vertical

CHAPTER 8: COMPETITIVE LANDSCAPE

8.1. KEY PLAYERS POSITIONING ANALYSIS, 2019

8.2. TOP WINNING STRATEGIES

8.3. COMPETITIVE DASHBOARD

8.4. KEY DEVELOPMENTS

8.4.1. Product launches

8.4.2. Partnership

8.4.3. Product development

8.4.4. Business expansion

8.4.5. Acquisition

CHAPTER 9: COMPANY PROFILE

9.1.3M

9.1.1. Company overview

9.1.2. Key executives

9.1.3. Company snapshot

9.1.4. Operating business segments

9.1.5. Product portfolio

9.1.6. R&D expenditure

9.1.7. Business performance

9.1.8. Key strategic moves and developments

9.2. ADVANCED MICRO DEVICES, INC.

9.2.1. Company overview

9.2.2. Key executives

9.2.3. Company snapshot

9.2.4. Operating business segments

9.2.5. Product portfolio

9.2.6. R&D expenditure

9.2.7. Business performance

9.2.8. Key strategic moves and developments

9.3. AMKOR TECHNOLOGY

- 9.3.1. Company overview
- 9.3.2. Key executives
- 9.3.3. Company snapshot
- 9.3.4. Product portfolio
- 9.3.5. R&D expenditure
- 9.3.6. Business performance
- 9.3.7. Key strategic moves and developments
- 9.4. APPLE INC.
 - 9.4.1. Company overview
 - 9.4.2. Key executives
 - 9.4.3. Company snapshot
 - 9.4.4. Operating business segments
 - 9.4.5. Product portfolio
 - 9.4.6. R&D expenditure
 - 9.4.7. Business performance
 - 9.4.8. Key strategic moves and developments
- 9.5. FUJITSU LIMITED
 - 9.5.1. Company overview
 - 9.5.2. Key Executives
 - 9.5.3. Company snapshot
 - 9.5.4. Operating business segments
 - 9.5.5. Product portfolio
 - 9.5.6. R&D Expenditure
 - 9.5.7. Business performance
 - 9.5.8. Key strategic moves and developments
- 9.6. INTEL CORPORATION
 - 9.6.1. Company overview
 - 9.6.2. Key executives
 - 9.6.3. Company snapshot
 - 9.6.4. Operating business segments
 - 9.6.5. Product portfolio
 - 9.6.6. R&D expenditure
 - 9.6.7. Business performance
 - 9.6.8. Key strategic moves and developments
- 9.7. INTERNATIONAL BUSINESS MACHINES CORPORATION
 - 9.7.1. Company overview
 - 9.7.2. Key Executives
 - 9.7.3. Company snapshot
 - 9.7.4. Operating business segments

- 9.7.5.Product portfolio
- 9.7.6.R&D expenditure
- 9.7.7.Business performance
- 9.7.8.Key strategic moves and developments
- 9.8.SAMSUNG ELECTRONICS CO., LTD.
- 9.8.1.Company overview
- 9.8.2.Key Executives
- 9.8.3.Company snapshot
- 9.8.4.Operating business segments
- 9.8.5.Product portfolio
- 9.8.6.R&D expenditure
- 9.8.7.Business performance
- 9.8.8.Key strategic moves and developments
- 9.9.TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED
- 9.9.1.Company overview
- 9.9.2.Key executives
- 9.9.3.Company snapshot
- 9.9.4.Product portfolio
- 9.9.5.R&D expenditure
- 9.9.6.Business performance
- 9.9.7.Key strategic moves and developments
- 9.10.TEXAS INSTRUMENTS INCORPORATED
- 9.10.1.Company overview
- 9.10.2.Key executives
- 9.10.3.Company snapshot
- 9.10.4.Operating business segments
- 9.10.5.Product portfolio
- 9.10.6.R&D expenditure
- 9.10.7.Business performance

List Of Tables

LIST OF TABLES

TABLE 01.COMPARISON BETWEEN THE PROPERTIES OF WIRE BONDING AND FLIP CHIP

TABLE 02.GLOBAL FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019-2027 (\$BILLION)

TABLE 03.FLIP CHIP MARKET REVENUE FOR 3D IC, BY REGION 2019–2027 (\$BILLION)

TABLE 04.FLIP CHIP MARKET REVENUE FOR2.5D IC, BY REGION 2019–2027 (\$BILLION)

TABLE 05.FLIP CHIP MARKET REVENUE FOR 2D IC, BY REGION 2019–2027 (\$BILLION)

TABLE 06.GLOBAL FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019-2027 (\$BILLION)

TABLE 07.FLIP CHIP MARKET REVENUE FORCOPPER PILLAR, BY REGION 2019–2027 (\$BILLION)

TABLE 08.FLIP CHIP MARKET REVENUE FORSOLDER BUMPING, BY REGION, 2019–2027 (\$BILLION)

TABLE 09.FLIP CHIP MARKET REVENUE FOR GOLD BUMPING, BY REGION 2019–2027 (\$BILLION)

TABLE 10.FLIP CHIP MARKET REVENUE FOR OTHERS, BY REGION 2019–2027 (\$BILLION)

TABLE 11.GLOBAL FLIP CHIP MARKET, BY INDUSTRY VERTICAL, 2019–2027 (\$BILLION)

TABLE 12.FLIP CHIP MARKET REVENUE FORELECTRONICS, BY REGION, 2019–2027 (\$BILLION)

TABLE 13.FLIP CHIP MARKET REVENUE FOR INDUSTRIAL, BY REGION, 2019–2027 (\$BILLION)

TABLE 14.GLOBAL FLIP CHIP MARKET REVENUE FOR HEALTHCARE, BY REGION 2019–2027 (\$BILLION)

TABLE 15.GLOBAL FLIP CHIP MARKET REVENUE FOR AUTOMOTIVE & TRANSPORT, BY REGION 2019–2027 (\$BILLION)

TABLE 16.GLOBAL FLIP CHIP MARKET REVENUE FOR IT & TELECOMMUNICATION, BY REGION 2019–2027 (\$BILLION)

TABLE 17.GLOBAL FLIP CHIP MARKET REVENUE FOR AEROSPACE & DEFENSE, BY REGION 2019–2027 (\$BILLION)

TABLE 18.GLOBAL FLIP CHIP MARKET REVENUE FOR OTHERS, BY REGION

2019–2027 (\$BILLION)

TABLE 19.FLIP CHIP MARKET REVENUE, BY REGION, 2019–2027 (\$BILLION)

TABLE 20.NORTH AMERICA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 21.NORTH AMERICA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 22.NORTH AMERICA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL, 2019–2027 (\$BILLION)

TABLE 23.NORTH AMERICA FLIP CHIP MARKET REVENUE, BY COUNTRY, 2019–2027 (\$BILLION)

TABLE 24.U.S. FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 25.U.S. FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 26.U.S. FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL 2019–2027 (\$BILLION)

TABLE 27.CANADA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 28.CANADA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 29.CANADA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL 2019–2027 (\$BILLION)

TABLE 30.EUROPE FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 31.EUROPE FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 32.EUROPE FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL, 2019–2027 (\$BILLION)

TABLE 33.EUROPE FLIP CHIP MARKET REVENUE, BY COUNTRY, 2019–2027 (\$BILLION)

TABLE 34.GERMANY FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 35.GERMANY FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 36.GERMANY FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL 2019–2027 (\$BILLION)

TABLE 37.FRANCE FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 38.FRANCE FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,

2019–2027 (\$BILLION)

TABLE 39.FRANCE FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 40.UK FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 41.UK FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 42.UK FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL 2019–2027
(\$BILLION)

TABLE 43.SPAIN FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 44.SPAIN FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 45.SPAIN FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 46.REST OF EUROPE FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 47.REST OF EUROPE FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 48.REST OF EUROPE FLIP CHIP MARKET REVENUE, BY INDUSTRY
VERTICAL 2019–2027 (\$BILLION)

TABLE 49.ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 50.ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 51.ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL,
2019–2027 (\$BILLION)

TABLE 52.ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY COUNTRY, 2019–2027
(\$BILLION)

TABLE 53.JAPAN FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 54.JAPAN FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 55.JAPAN FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 56.CHINA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 57.CHINA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 58.CHINA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 59.INDIA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 60.INDIA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 61.INDIA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 62.AUSTRALIA FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 63.AUSTRALIA FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 64.AUSTRALIA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL
2019–2027 (\$BILLION)

TABLE 65.REST OF ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 66.REST OF ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 67.REST OF ASIA-PACIFIC FLIP CHIP MARKET REVENUE, BY INDUSTRY
VERTICAL 2019–2027 (\$BILLION)

TABLE 68.LAMEA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 69.LAMEA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY,
2019–2027 (\$BILLION)

TABLE 70.LAMEA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL,
2019–2027 (\$BILLION)

TABLE 71.LAMEA FLIP CHIP MARKET REVENUE, BY COUNTRY, 2019–2027
(\$BILLION)

TABLE 72.LATIN AMERICA FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 73.LATIN AMERICA FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 74.LATIN AMERICA FLIP CHIP MARKET REVENUE, BY INDUSTRY
VERTICAL 2019–2027 (\$BILLION)

TABLE 75.MIDDLE EAST FLIP CHIP MARKET REVENUE, BY PACKAGING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 76.MIDDLE EAST FLIP CHIP MARKET REVENUE, BY BUMPING
TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 77.MIDDLE EAST FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL

2019–2027 (\$BILLION)

TABLE 78.AFRICA FLIP CHIP MARKET REVENUE, BY PACKAGING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 79.AFRICA FLIP CHIP MARKET REVENUE, BY BUMPING TECHNOLOGY, 2019–2027 (\$BILLION)

TABLE 80.AFRICA FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL 2019–2027 (\$BILLION)

TABLE 81.KEY NEW PRODUCT LAUNCHES (2016-2019)

TABLE 82.PARTNERSHIP (2016-2019)

TABLE 83.PRODUCT DEVELOPMENT (2016-2019)

TABLE 84.KEY EXPANSION (2016-2019)

TABLE 85.KEY ACQUISITION (2016-2019)

TABLE 86.3M: KEY EXECUTIVES

TABLE 87.3M: COMPANY SNAPSHOT

TABLE 88.3M: OPERATING SEGMENTS

TABLE 89.3M: PRODUCT PORTFOLIO

TABLE 90.3M: KEY STRATEGIC MOVES AND DEVELOPMENTS

TABLE 91.ADVANCED MICRO DEVICES, INC.: KEY EXECUTIVES

TABLE 92.ADVANCED MICRO DEVICES, INC.: COMPANY SNAPSHOT

TABLE 93.ADVANCED MICRO DEVICES, INC.: OPERATING SEGMENTS

TABLE 94.ADVANCED MICRO DEVICES, INC.: PRODUCT PORTFOLIO

TABLE 95.AMKOR TECHNOLOGY.: COMPANY SNAPSHOT

TABLE 96.AMKOR TECHNOLOGY: VIDEO ANALYTICS PRODUCT PORTFOLIO

TABLE 97.APPLE INC.: KEY EXECUTIVES

TABLE 98.APPLE INC.: COMPANY SNAPSHOT

TABLE 99.APPLE INC.: PRODUCT CATEGORIES

TABLE 100.APPLE INC.: PRODUCT PORTFOLIO

TABLE 101.FUJITSU LIMITED: KEY EXECUTIVES

TABLE 102.FUJITSU LIMITED: COMPANY SNAPSHOT

TABLE 103.FUJITSU LIMITED: OPERATING SEGMENTS

TABLE 104.FUJITSU LIMITED: PRODUCT PORTFOLIO

TABLE 105.INTEL CORPORATION: KEY EXECUTIVES

TABLE 106.INTEL CORPORATION: COMPANY SNAPSHOT

TABLE 107.INTEL CORPORATION: OPERATING SEGMENTS

TABLE 108.INTEL CORPORATION: VIDEO ANALYTICS PRODUCT PORTFOLIO

TABLE 109.INTERNATIONAL BUSINESS MACHINES CORPORATION: KEY EXECUTIVES

TABLE 110.INTERNATIONAL BUSINESS MACHINES CORPORATION: COMPANY SNAPSHOT

TABLE 111.INTERNATIONAL BUSINESS MACHINES CORPORATION: OPERATING SEGMENTS

TABLE 112.INTERNATIONAL BUSINESS MACHINES CORPORATION: PRODUCT PORTFOLIO

TABLE 113.SAMSUNG ELECTRONICS CO., LTD.: KEY EXECUTIVES

TABLE 114.SAMSUNG ELECTRONICS CO., LTD.: COMPANY SNAPSHOT

TABLE 115.SAMSUNG ELECTRONICS CO., LTD.: OPERATING SEGMENTS

TABLE 116.SAMSUNG ELECTRONICS CO., LTD.: PRODUCT PORTFOLIO

TABLE 120.TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED: KEY STRATEGIC MOVES AND DEVELOPMENTS

TABLE 121.TEXAS INSTRUMENTS INCORPORATED: KEY EXECUTIVES

TABLE 122.TEXAS INSTRUMENTS INCORPORATED: COMPANY SNAPSHOT

TABLE 123.TEXAS INSTRUMENTS INCORPORATED: OPERATING SEGMENTS

TABLE 124.TEXAS INSTRUMENTS INCORPORATED: PRODUCT PORTFOLIO

List Of Figures

LIST OF FIGURES

FIGURE 01.KEY MARKET SEGMENTS

FIGURE 02.GLOBAL FLIP CHIP MARKET, 2019–2027

FIGURE 03.GLOBAL FLIP CHIP MARKET, BY REGION, 2019–2027

FIGURE 04.TOP IMPACTING FACTORS

FIGURE 05.TOP INVESTMENT POCKETS

FIGURE 06.TOP PLAYERS OF THE GLOBAL FLIP CHIP MARKET

FIGURE 07.MODERATE-TO-HIGH BARGAINING POWER OF SUPPLIERS

FIGURE 08.MODERATE-TO-HIGH BARGAINING POWER OF BUYER

FIGURE 09.MODERATE-TO-HIGH THREAT OF SUBSTITUTES

FIGURE 10.MODERATE-TO-HIGH THREAT OF NEW ENTRANTS

FIGURE 11.LOW-TO-HIGH COMPETITIVE RIVALRY

FIGURE 12.VALUE CHAIN ANALYSIS OF FLIP CHIP MARKET

FIGURE 13.MARKET DYNAMICS: GLOBAL FLIP CHIP MARKET

FIGURE 14.GLOBAL FLIP CHIP MARKET, BY PACKAGING TECHNOLOGY,
2019-2027

FIGURE 15.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR
3D IC, BY COUNTRY, 2018 &2026 (%)

FIGURE 16.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR
2.5D IC, BY COUNTRY, 2018 &2026 (%)

FIGURE 17.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR
2D IC, BY COUNTRY, 2018 & 2026 (%)

FIGURE 18.GLOBAL FLIP CHIP MARKET, BY BUMPING TECHNOLOGY, 2019–2027

FIGURE 19.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR
COPPER PILLAR, BY COUNTRY, 2018 & 2026(%)

FIGURE 20.COMPARATIVE SHARE ANALYSIS OF GLOBAL FLIP CHIP MARKET
FOR SOLDER BUMPING, BY COUNTRY, 2018 & 2026 (%)

FIGURE 21.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET GOLD
BUMPING, BY COUNTRY, 2018 & 2026 (%)

FIGURE 22.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR
OTHERS, BY COUNTRY, 2018 &2026 (%)

FIGURE 23.GLOBAL FLIP CHIP MARKET REVENUE, BY INDUSTRY VERTICAL,
2019–2027 (\$BILLION)

FIGURE 24.COMPARATIVE SHARE ANALYSIS OF GLOBAL FLIP CHIP MARKET
FOR ELECTRONICS, BY COUNTRY, 2018 &2026 (%)

FIGURE 25.COMPARATIVE SHARE ANALYSIS OF GLOBAL FLIP CHIP MARKET

- FOR INDUSTRIAL, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 26.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR HEALTHCARE, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 27.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR AUTOMOTIVE & TRANSPORT, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 28.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR IT & TELECOMMUNICATION, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 29.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR AEROSPACE & DEFENSE, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 30.COMPARATIVE SHARE ANALYSIS GLOBAL FLIP CHIP MARKET FOR OTHERS, BY COUNTRY, 2018 & 2026 (%)
- FIGURE 31.FLIP CHIP MARKET REVENUE, BY REGION, 2019–2027 (\$BILLION)
- FIGURE 32.U.S. FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 33.CANADA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 34.GERMANY FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 35.FRANCE FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 36.UK FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 37.SPAIN FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 38.REST OF EUROPE FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 39.JAPAN FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 40.CHINA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 41.INDIA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 42.AUSTRALIA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 43.REST OF ASIA-PACIFIC FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 44.LATIN AMERICA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 45.MIDDLE EAST FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 46.AFRICA FLIP CHIP MARKET REVENUE, 2019–2027 (\$BILLION)
- FIGURE 47.KEY PLAYER POSITIONING ANALYSIS: GLOBAL FLIP CHIP MARKET
- FIGURE 48.TOP WINNING STRATEGIES, BY YEAR, 2017-2020
- FIGURE 49.TOP WINNING STRATEGIES, BY DEVELOPMENT, 2017-2020
- FIGURE 50.TOP WINNING STRATEGIES, BY COMPANY, 2017-2020
- FIGURE 51.COMPETITIVE DASHBOARD
- FIGURE 52.COMPETITIVE DASHBOARD
- FIGURE 53.COMPETITIVE HEATMAP OF KEY PLAYERS
- FIGURE 54.3M: R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 55.3M: REVENUE, 2017–2019 (\$BILLION)
- FIGURE 56.3M: REVENUE SHARE BY SEGMENT, 2019 (%)

- FIGURE 57.3M: REVENUE SHARE BY REGION, 2019 (%)
- FIGURE 58.3M: R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 59.ADVANCED MICRO DEVICES, INC.: REVENUE, 2017–2019 (\$BILLION)
- FIGURE 60.ADVANCED MICRO DEVICES, INC.: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 61.ADVANCED MICRO DEVICES, INC.: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 62.AMKOR TECHNOLOGY: KEY EXECUTIVES
- FIGURE 63.AMKOR TECHNOLOGY: R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 64.AMKOR TECHNOLOGY: REVENUE, 2017–2019 (\$BILLION)
- FIGURE 65.AMKOR TECHNOLOGY: REVENUE SHARE BY REGION, 2019 (%)
- FIGURE 66.R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 67.APPLE INC.: REVENUE, 2017–2019 (\$MILLION)
- FIGURE 68.APPLE INC.: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 69.APPLE INC.: REVENUE SHARE BY REGION, 2019 (%)
- FIGURE 70.R&D EXPENDITURE, 2016–2018 (\$MILLION)
- FIGURE 71.FUJITSU LIMITED: REVENUE, 2016–2018 (\$MILLION)
- FIGURE 72.FUJITSU LIMITED: REVENUE SHARE BY SEGMENT, 2018 (%)
- FIGURE 73.FUJITSU LIMITED: REVENUE SHARE BY REGION, 2018 (%)
- FIGURE 74.R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 75.INTEL CORPORATION: REVENUE, 2017–2019 (\$MILLION)
- FIGURE 76.INTEL CORPORATION: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 77.R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 78.INTERNATIONAL BUSINESS MACHINES CORPORATION: REVENUE, 2017–2019 (\$MILLION)
- FIGURE 79.INTERNATIONAL BUSINESS MACHINES CORPORATION: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 80.INTERNATIONAL BUSINESS MACHINES CORPORATION: REVENUE SHARE BY REGION, 2019 (%)
- FIGURE 81.R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 82.SAMSUNG ELECTRONICS CO., LTD.: REVENUE, 2017–2019 (\$MILLION)
- FIGURE 83.SAMSUNG ELECTRONICS CO., LTD.: REVENUE SHARE BY SEGMENT, 2019 (%)
- FIGURE 84.SAMSUNG ELECTRONICS CO., LTD.: REVENUE SHARE BY REGION, 2019 (%)
- FIGURE 85.R&D EXPENDITURE, 2017–2019 (\$MILLION)
- FIGURE 86.TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED: REVENUE, 2017–2019 (\$MILLION)

FIGURE 87.TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED:
REVENUE SHARE BY REGION, 2019 (%)

FIGURE 88.R&D EXPENDITURE, 2017–2019 (\$MILLION)

FIGURE 89.TEXAS INSTRUMENTS INCORPORATED: REVENUE, 2017–2019
(\$MILLION)

FIGURE 90.TEXAS INSTRUMENTS INCORPORATED: REVENUE SHARE BY
SEGMENT, 2019 (%)

FIGURE 91.TEXAS INSTRUMENTS INCORPORATED: REVENUE SHARE BY
REGION, 2019 (%)

COMPANIES MENTIONED

3M, Advanced Micro Devices, Inc., Amkor Technology, Apple Inc., Fujitsu Limited, Intel Corporation, International Business Machines Corporation, Samsung Electronics Co., Ltd., Taiwan Semiconductor Manufacturing Company Limited, and Texas Instruments Incorporated.

I would like to order

Product name: Flip Chip Market by Packaging Technology (3D IC, 2.5D IC, and 2D IC), Bumping Technology (Solder Bumping, Gold Bumping, and Others), and Industry (Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace & Defense, and Others): Global Opportunity Analysis and Industry Forecast, 2020–2027

Product link: <https://marketpublishers.com/r/FC852983D2BEN.html>

Price: US\$ 5,769.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/FC852983D2BEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970